

Notice of References Cited	Application/Control No. 10/710,522	Applicant(s)/Patent Under Reexamination CHEN, CHUNG-CHIH	
	Examiner TabassomT Tadayyon-Eslami	Art Unit 1709	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,361,614	03-2002	Chung et al.	134/3
	B	US-			
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	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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